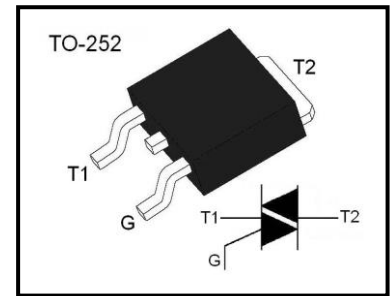


Description

Glass passivated triacs in a plastic envelope, intended for use in applications requiring high bidirectional transient and blocking voltage capability and high thermal cycling performance. Typical applications include motor control, industrial and domestic lighting, heating and static switching.



Absolute Maximum Values

Parameter	Symbol	Conditions		Value	Unit
Repetitive peak off-state voltages	V _{DRM}	T _j = 25°C		600	V
Repetitive peak reverse voltages	V _{RRM}	T _j = 25°C		600	V
On-state RMS current	I _{T(RMS)}	full sine wave; T _C ≤ 68°C		8	A
Non repetitive surge peak on-state current	I _{TSM}	full cycle ,T _j = 25°C	t=20 ms	65	A
			t=16.7ms	72	
I ² t value for fusing	I ² t	t = 10ms, T _j = 25°C		21	A ² s
Critical rate of rise of on-state current	di/dt	I _G =2I _{GT} , f=100Hz T _j = 25°C	I - II -III	80	A/μs
			IV	40	
Peak gate current	I _{GM}	t _p = 20μs, T _j = 125°C		4	A
Peak gate power	P _{GM}			10	W
Average gate power	P _{G(AV)}	T _j = 125°C		0.5	W
Peak pulse voltage	V _{pp}	T _j = 25°C, repetitive,off-state		4	kW
Operating junction temperature	T _j			-40 ~ 125	°C
Storage Temperature	T _{stg}			-40 ~ 150	°C

Thermal Resistances

Parameter	Symbol	Value	Unit
Junction to case (AC)	$R_{th(j-c)}$	5	$^\circ\text{C}/\text{W}$
Junction to ambient (AC)	$R_{th(j-a)}$	130	$^\circ\text{C}/\text{W}$

Static Characteristics ($T_j = 25\text{ }^{\circ}\text{C}$ unless otherwise stated)

Parameter	Symbol	Conditions		Min	Typ	Max	Unit
Gate trigger current	I_{GT}	$V_D = 12\text{ V}$, $R_L = 33\Omega$	I - II - III			10	mA
			IV			25	
Gate trigger voltage	V_{GT}	$V_D = 12\text{ V}$, $R_L = 33\Omega$	ALL			1	V
Gate non trigger voltage	V_{GD}	$V_D = V_{DRM}$, $T_j = 125^{\circ}\text{C}$ $R_L = 3.3\text{k}\Omega$	ALL	0.2			V
Latching current	I_L	$I_G = 2I_{GT}$	I - III - IV			20	mA
			II			35	
Holding current	I_H	$I_T = 500\text{ mA}$				20	mA
On-state voltage	V_{TM}	$I_T = 10\text{ A}$, $t_p = 380\mu\text{s}$			1.2	1.5	V
Threshold voltage	V_{TO}	$T_j = 125^{\circ}\text{C}$				0.8	V
Dynamic resistance	R_D	$T_j = 125^{\circ}\text{C}$				53	$\text{m}\Omega$
Off-state leakage current Off-state reverse current	I_{DRM} I_{RRM}	$V_D = V_{DRM}$ $V_R = V_{RRM}$	$T_j = 25^{\circ}\text{C}$			5	μA
			$T_j = 125^{\circ}\text{C}$			0.35	mA

Dynamic Characteristics $T_j = 25\text{ }^{\circ}\text{C}$ unless otherwise stated

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Critical rate of rise of off-state voltage	dV/dt	$V_D = 400\text{ V}$, gate open, $T_j = 125^{\circ}\text{C}$	50			$\text{V}/\mu\text{s}$
Critical rate of change Of commutating voltage	$(dV/dt)_c$	$(dI/dt)_c = 2.7\text{ A/ms}$, $T_j = 125^{\circ}\text{C}$	5			$\text{V}/\mu\text{s}$
Gate turn-on time	t_{on}	$I_G = 40\text{ mA}$; $I_A = 200\text{ mA}$, $I_R = 20\text{ mA}$		1.5		μs
Gate turn-off time	t_{off}			15		

Typical Characteristics

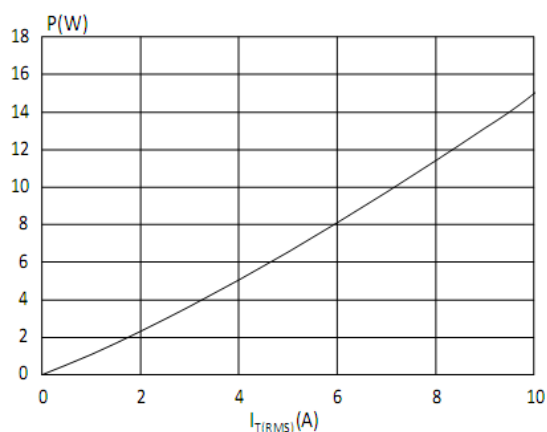


Fig.1. Maximum power dissipation versus RMS on state current

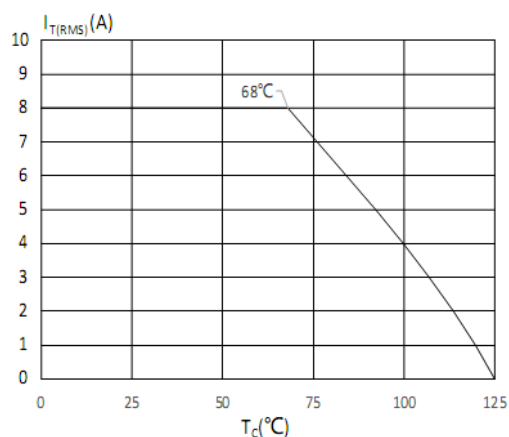


Fig.2. RMS on state current versus case temperature

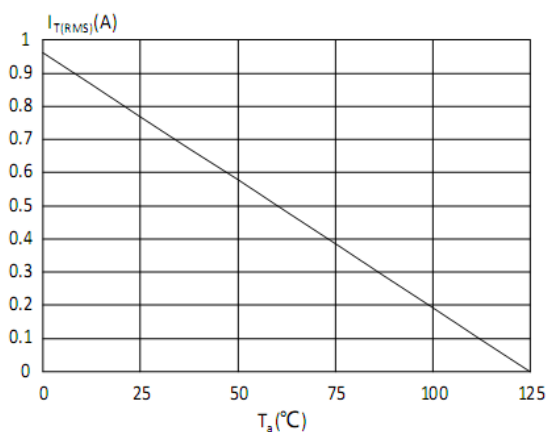


Fig.3. RMS on state current versus ambient temperature (printed circuit board FR4, copper thickness: 35μm) (full cycle)

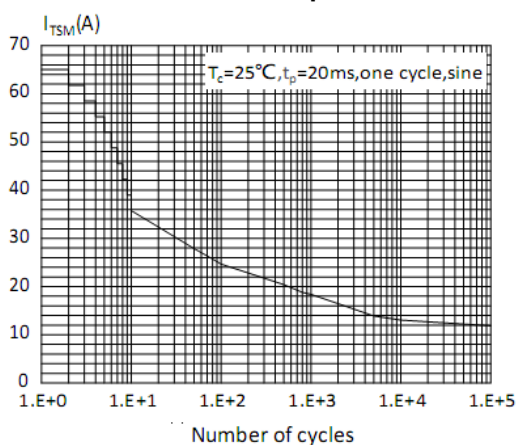


Fig.4. Surge peak on state current versus number of cycles

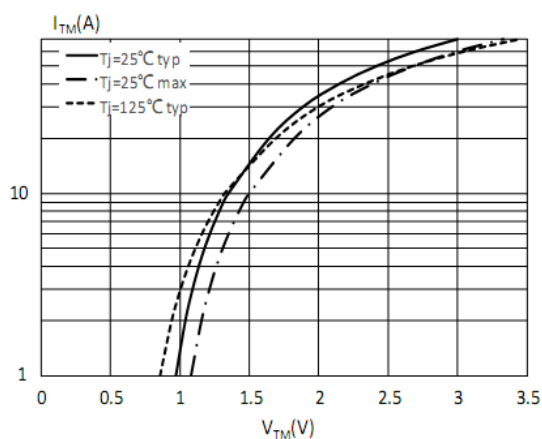


Fig.5. On state characteristics

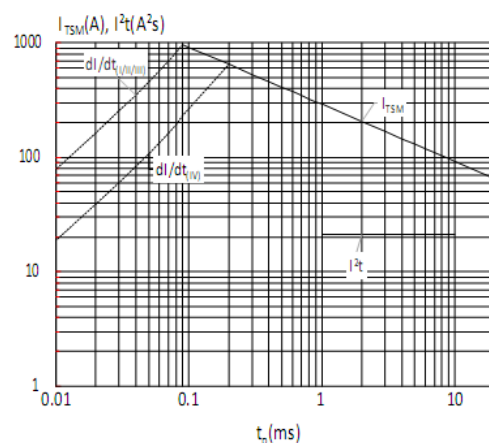


Fig.6. Non repetitive surge peak on state current for a sinusoidal pulse with width $t_p < 20\text{ms}$, and corresponding value of $I^2 t$ (I - II - III) $dl/dt < 80\text{A}/\mu\text{s}$; IV: $dl/dt < 40\text{A}/\mu\text{s}$)

Package Dimensions

Dim	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.50	0.087	0.098
A1	0.00	0.12	0.000	0.005
A2	2.20	2.40	0.087	0.094
B	1.20	1.60	0.047	0.063
b	0.50	0.70	0.020	0.028
b1	0.70	0.90	0.028	0.035
c	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.35	6.65	0.250	0.262
D1	5.20	5.40	0.205	0.213
E	5.40	5.70	0.213	0.224
e	2.20	2.40	0.087	0.094
e1	4.40	4.80	0.173	0.189
L	9.60	10.20	0.378	0.402
L1	2.70	3.10	0.106	0.122
L2	1.40	1.80	0.055	0.071
L3	0.90	1.50	0.035	0.059